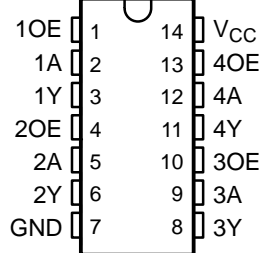


- Operates From 1.65 V to 3.6 V
- Max t_{pd} of 3.1 ns at 3.3 V
- ± 24 -mA Output Drive at 3.3 V
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Performance Tested Per JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

D, DGV, NS, OR PW PACKAGE
(TOP VIEW)



DESCRIPTION/ORDERING INFORMATION

This quadruple bus buffer gate is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVC126 features independent line drivers with 3-state outputs. Each output is disabled when the associated output-enable (OE) input is low.

To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

ORDERING INFORMATION

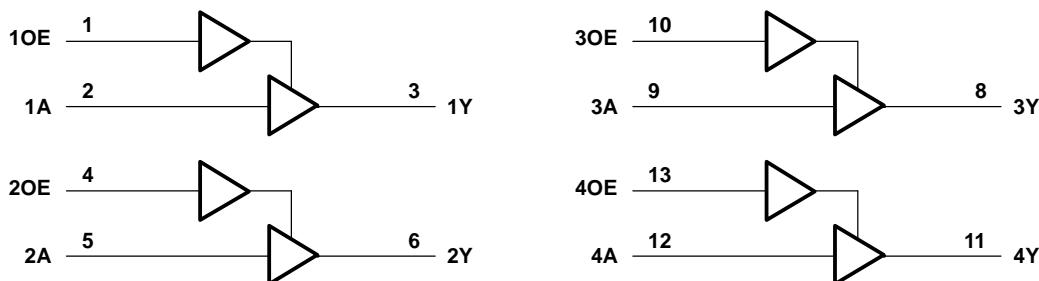
T_A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SOIC - D	Tube of 50	SN74ALVC126D	ALVC126
		Reel of 2500	SN74ALVC126DR	
	SOP - NS	Reel of 2000	SN74ALVC126NSR	ALVC126
	TSSOP - PW	Reel of 2000	SN74ALVC126PWR	VA126
	TVSOP - DGV	Reel of 2000	SN74ALVC126DGVR	VA126

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each buffer)

INPUTS		OUTPUT Y
OE	A	
H	H	H
H	L	L
L	X	Z

Logic Diagram (positive logic)



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SN74ALVC126

QUADRUPLE BUS BUFFER GATE WITH 3-STATE OUTPUTS

SCES111H–JULY 1997–REVISED DECEMBER 2003

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		UNIT
Supply voltage range, V_{CC}		-0.5 V to 4.6 V
Input voltage range, V_I (see ⁽²⁾)		-0.5 V to 4.6 V
Output voltage range, V_O (see ⁽²⁾ and ⁽³⁾)		-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)		-50 mA
Output clamp current, I_{OK} ($V_O < 0$)		-50 mA
Continuous output current, I_O		± 50 mA
Continuous current through V_{CC} or GND		± 100 mA
Package thermal impedance, θ_{JA} (see ⁽⁴⁾)	D package	86°C/W
	DGV package	127°C/W
	NS package	76°C/W
	PW package	113°C/W
Storage temperature range, T_{stg}		-65°C to 150°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 4.6 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

			MIN	MAX	UNIT
V_{CC}	Supply voltage		1.65	3.6	V
V_{IH}	High-level input voltage	$V_{CC} = 1.65$ V to 1.95 V	$0.65 \times V_{CC}$		V
		$V_{CC} = 2.3$ V to 2.7 V	1.7		
		$V_{CC} = 2.7$ V to 3.6 V	2		
V_{IL}	Low-level input voltage	$V_{CC} = 1.65$ V to 1.95 V		$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3$ V to 2.7 V		0.7	
		$V_{CC} = 2.7$ V to 3.6 V		0.8	
V_I	Input voltage		0	3.6	V
V_O	Output voltage		0	V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 1.65$ V		-4	mA
		$V_{CC} = 2.3$ V		-12	
		$V_{CC} = 2.7$ V		-12	
		$V_{CC} = 3$ V		-24	
I_{OL}	Low-level output current	$V_{CC} = 1.65$ V		4	mA
		$V_{CC} = 2.3$ V		12	
		$V_{CC} = 2.7$ V		12	
		$V_{CC} = 3$ V		24	
$\Delta t/\Delta v$	Input transition rise or fall rate			5	ns/V
T_A	Operating free-air temperature		-40	85	°C

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP ⁽¹⁾	MAX	UNIT
V_{OH}		$I_{OH} = -100 \mu A$	1.65 V to 3.6 V	$V_{CC}-0.2$			V
		$I_{OH} = -4 \text{ mA}$	1.65 V	1.2			
		$I_{OH} = -6 \text{ mA}$	2.3 V	2			
			2.3 V	1.7			
		$I_{OH} = -12 \text{ mA}$	2.7 V	2.2			
			3 V	2.4			
		$I_{OH} = -24 \text{ mA}$	3 V	2			
V_{OL}		$I_{OL} = 100 \mu A$	1.65 V to 3.6 V	0.2			V
		$I_{OL} = 4 \text{ mA}$	1.65 V	0.45			
		$I_{OL} = 6 \text{ mA}$	2.3 V	0.4			
			2.3 V	0.7			
		$I_{OL} = 12 \text{ mA}$	2.7 V	0.4			
		$I_{OL} = 24 \text{ mA}$	3 V	0.55			
I_I		$V_I = V_{CC}$ or GND	3.6 V	± 5			μA
I_{OZ}		$V_O = V_{CC}$ or GND	3.6 V	± 10			μA
I_{CC}		$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V	10			μA
ΔI_{CC}		One input at $V_{CC} - 0.6 \text{ V}$, Other inputs at V_{CC} or GND	3 V to 3.6 V	750			μA
C_i	Control inputs	$V_I = V_{CC}$ or GND	3.3 V	3.5			pF
	Data inputs			3.5			
C_o	Outputs	$V_O = V_{CC}$ or GND	3.3 V	5.5			pF

(1) All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^\circ\text{C}$.

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$		$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$		$V_{CC} = 2.7 \text{ V}$		$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A	Y	1.3	5.6	1	3.4	3.4		1.1	3.1	ns
t_{en}	OE	Y	1	5.9	1	3.8	3.8		1	3.3	ns
t_{dis}	OE	Y	1.8	5.6	1	3.3	4.4		1	3.7	ns

OPERATING CHARACTERISTICS, $T_A = 25^\circ\text{C}$

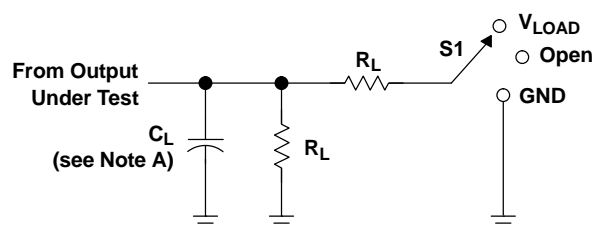
PARAMETER			TEST CONDITIONS	$V_{CC} = 1.8 \text{ V}$	$V_{CC} = 2.5 \text{ V}$	$V_{CC} = 3.3 \text{ V}$	UNIT
				TYP	TYP	TYP	
C_{pd}	Power dissipation capacitance per gate	Outputs enabled	$C_L = 0$, $f = 10 \text{ MHz}$	15	17	19	pF
		Outputs disabled		2	2	3	

SN74ALVC126

QUADRUPLE BUS BUFFER GATE WITH 3-STATE OUTPUTS

SCES111H—JULY 1997—REVISED DECEMBER 2003

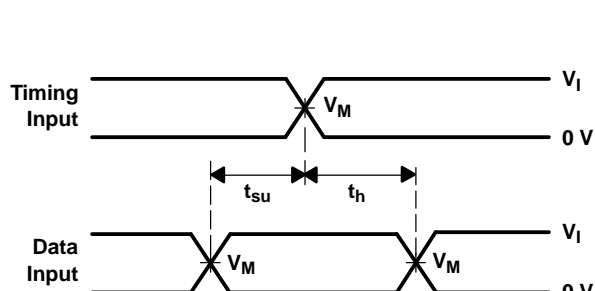
PARAMETER MEASUREMENT INFORMATION



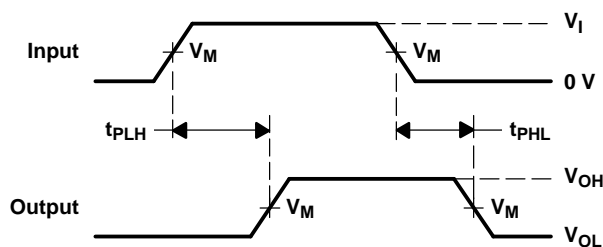
LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

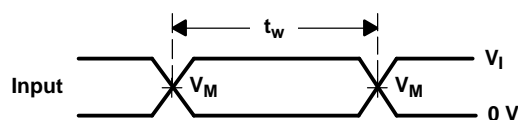
V_{CC}	INPUT		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_I	t_r/t_f					
$1.8 V \pm 0.15 V$	V_{CC}	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$2.5 \pm 0.2 V$	V_{CC}	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	$\leq 2.5 \text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V
$3.3 V \pm 0.3 V$	2.7 V	$\leq 2.5 \text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V



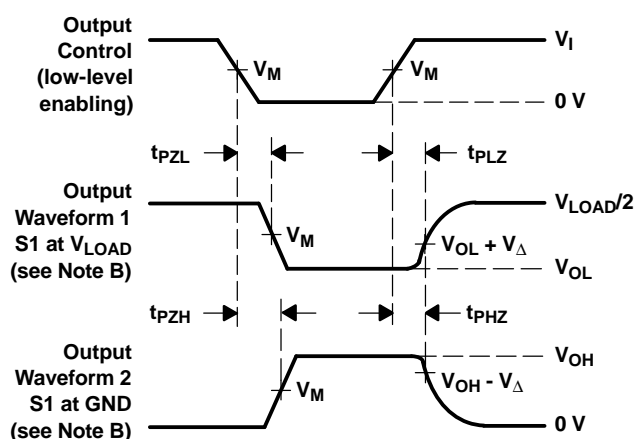
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .
 - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

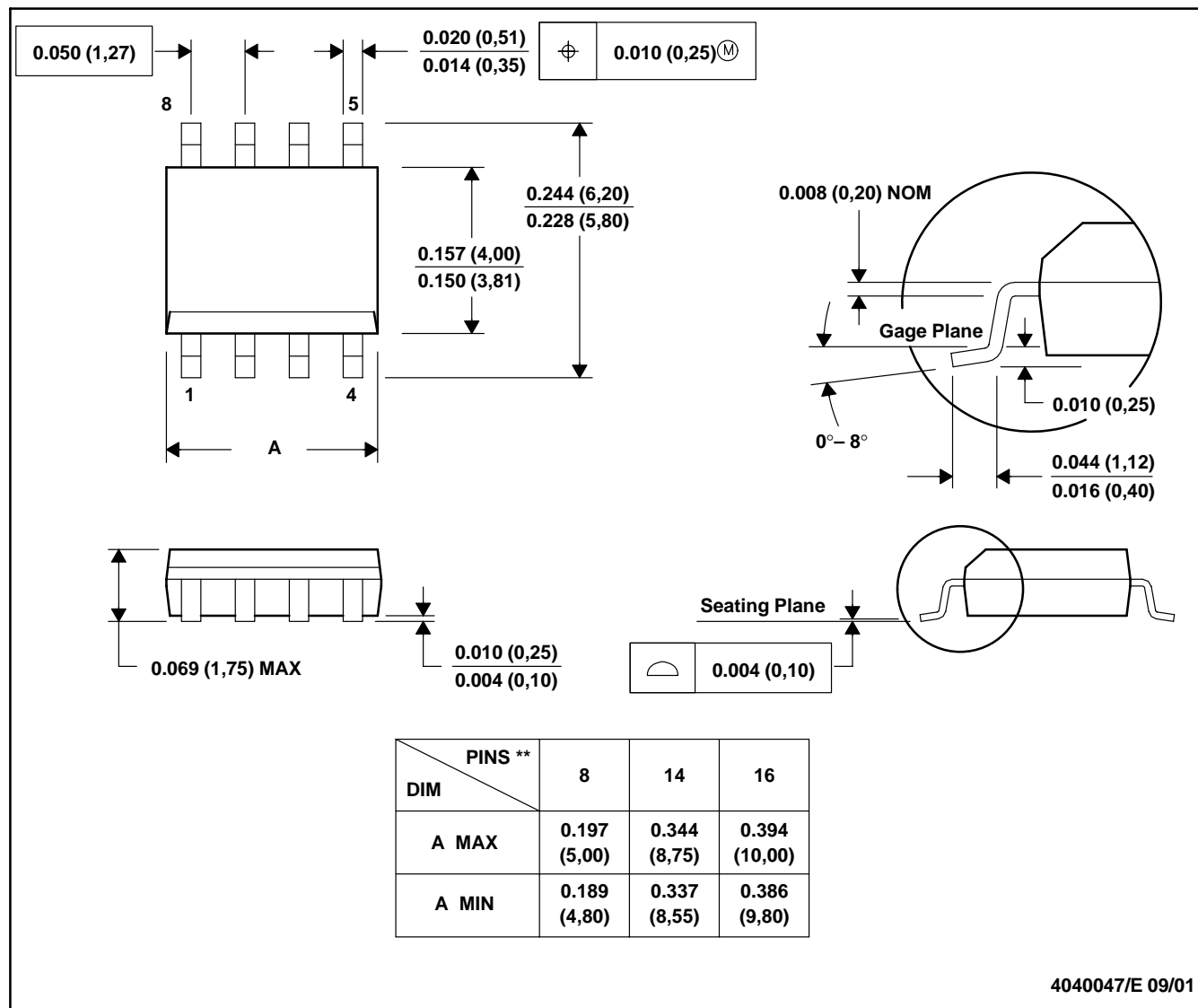
DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

D (R-PDSO-G)****PLASTIC SMALL-OUTLINE PACKAGE****8 PINS SHOWN**

- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
 D. Falls within JEDEC MS-012

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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